



Material Content Data Sheet



Sales Product Name		BTS3256D		Issued		27. September 2017		
MA#		MA000521270						
Package		PG-TO252-5-11		Weight*		358.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.154	1.44	1.44	14359	14359
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		570	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		171	
	non noble metal	copper	7440-50-8	204.243	56.90	56.98	568957	569698
wire	non noble metal	aluminium	7429-90-5	18.468	5.14	5.14	51447	51447
encapsulation	organic material	carbon black	1333-86-4	1.223	0.34		3406	
	plastics	epoxy resin	-	21.399	5.96		59612	
	inorganic material	silicondioxide	60676-86-0	99.660	27.76	34.06	277620	340638
leadfinish	non noble metal	tin	7440-31-5	5.072	1.41	1.41	14130	14130
plating	non noble metal	nickel	7440-02-0	0.076	0.02		212	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	213
glue	plastics	Polyimide	26023-21-2	0.155	0.04	0.04	430	430
solder	noble metal	silver	7440-22-4	0.082	0.02		227	
	non noble metal	tin	7440-31-5	0.065	0.02		182	
	non noble metal	lead	7439-92-1	3.114	0.87	0.91	8676	9085
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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